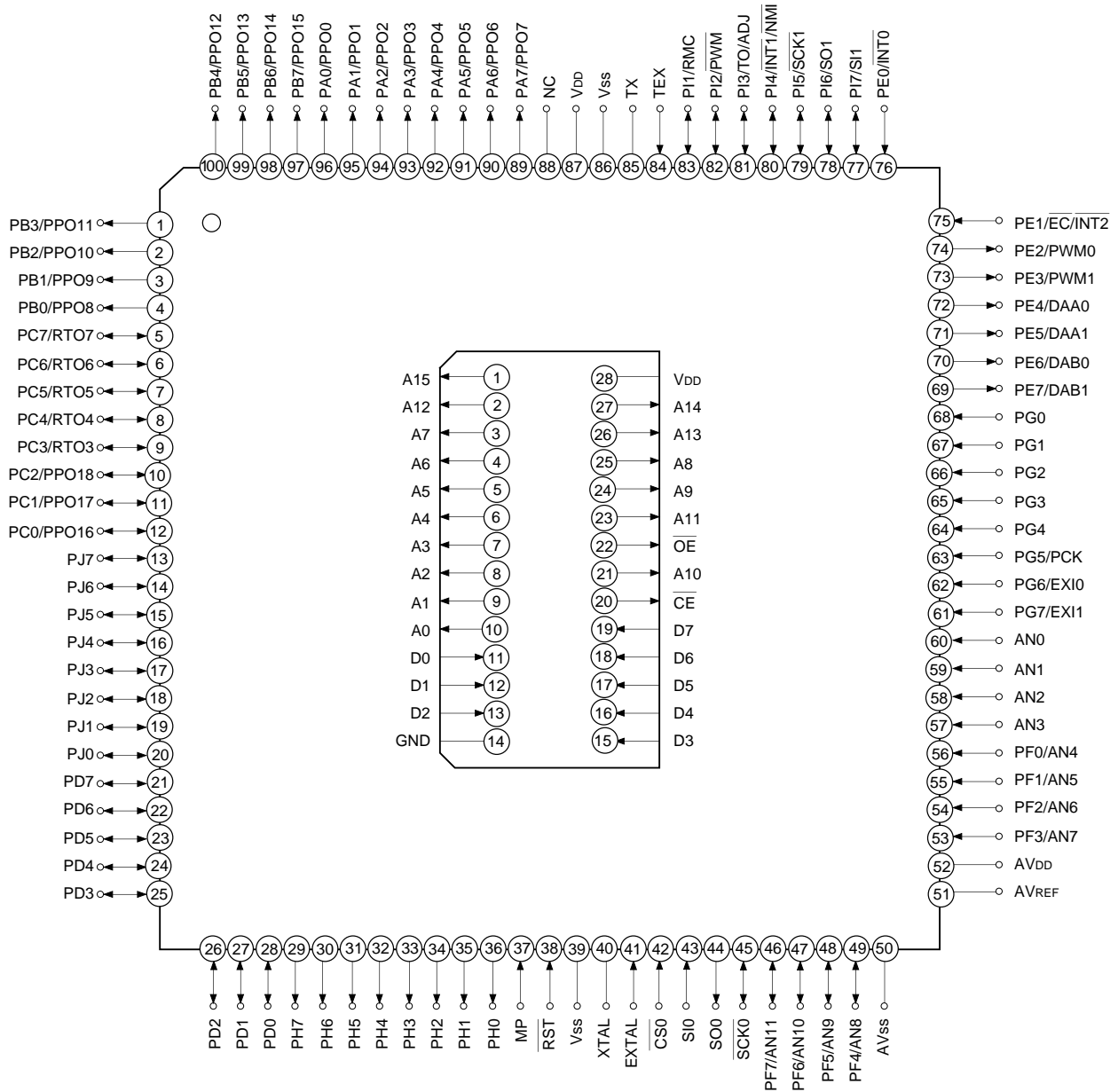




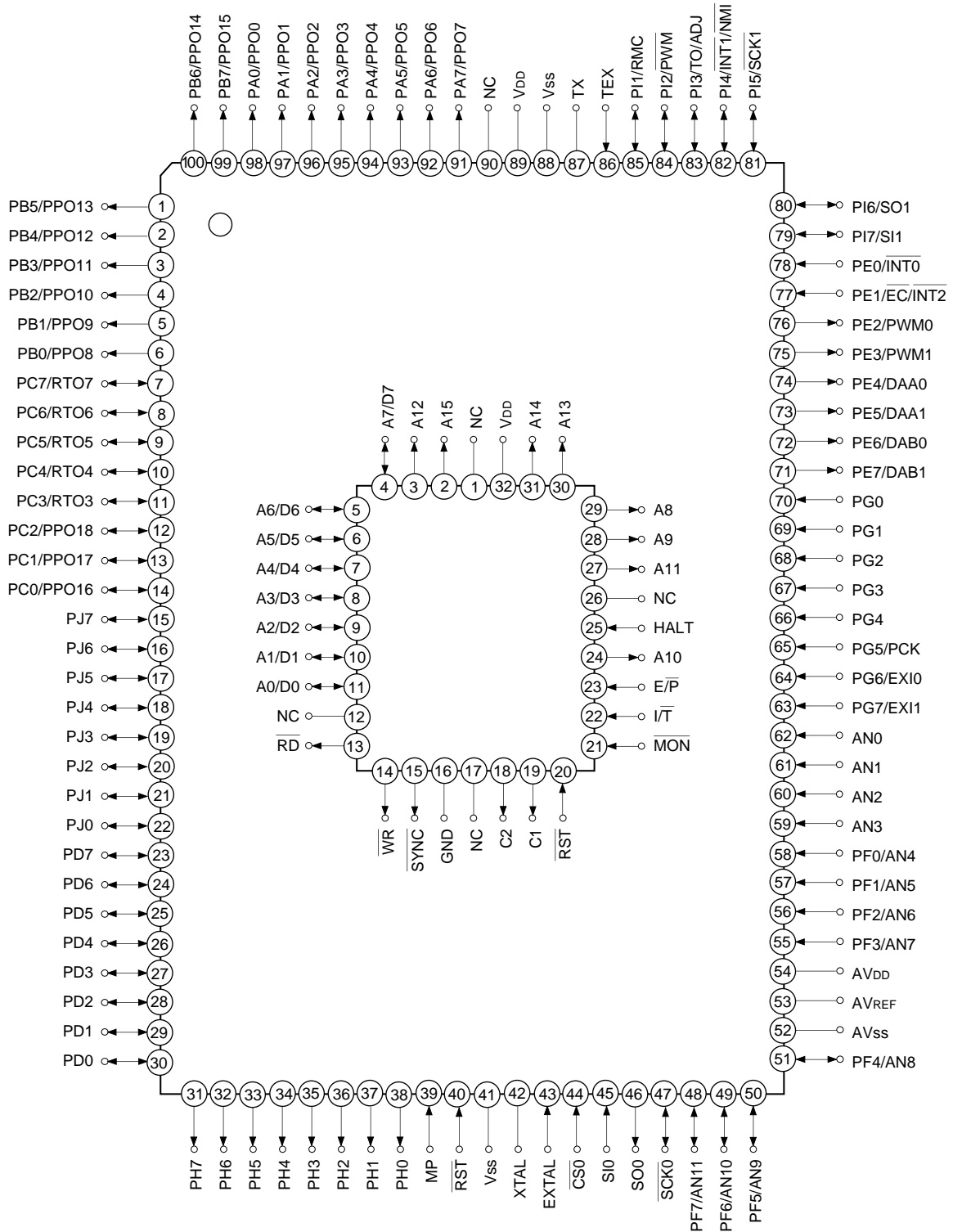


Pin Assignment in Piggyback Mode (LQFP package)



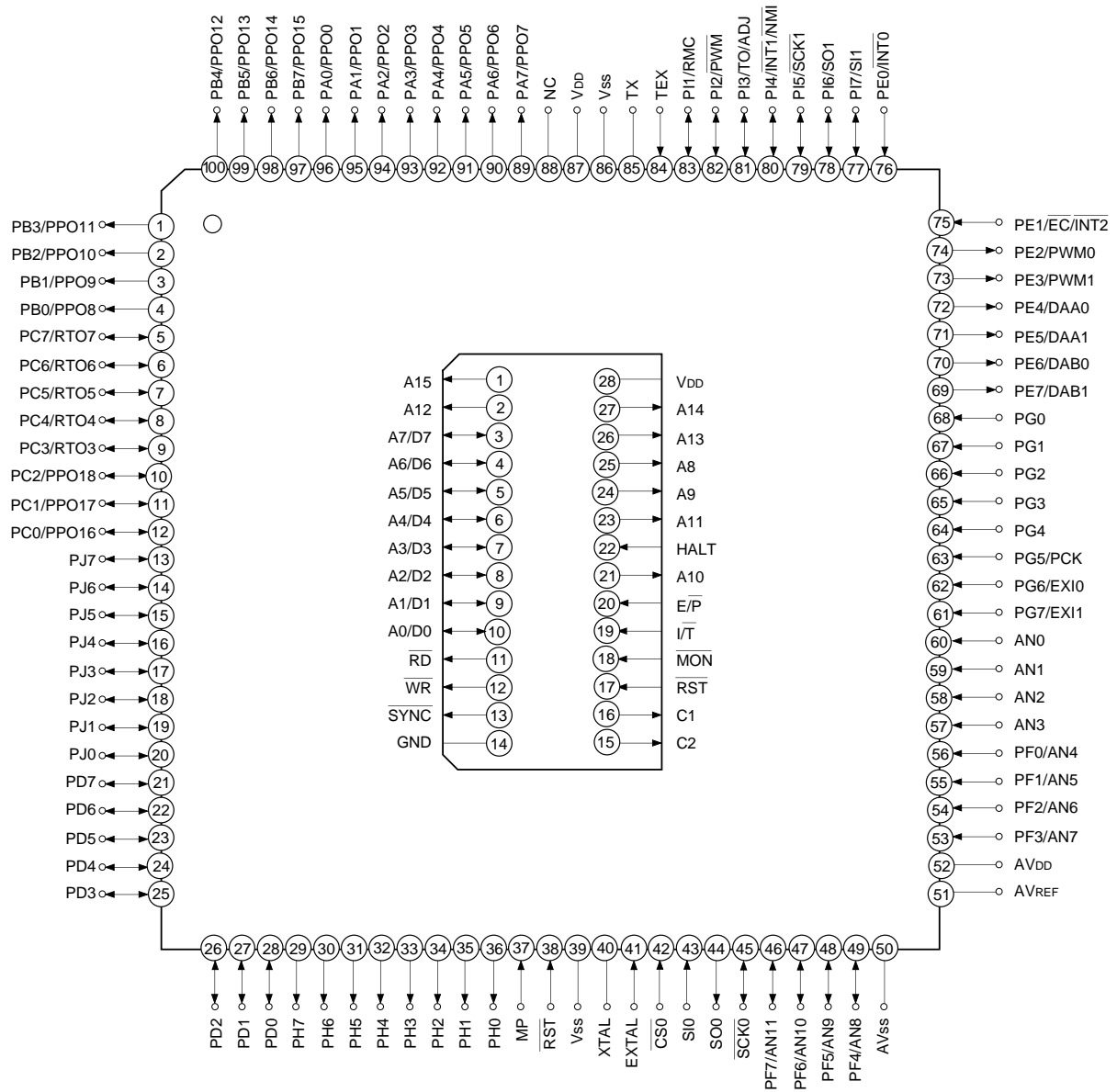
- Note)**
1. NC (Pin 88) is always connected to V<sub>DD</sub>.
  2. V<sub>ss</sub> (Pins 39 and 86) are both connected to GND.
  3. MP (Pin 37) is always connected to GND.

Pin Assignment in Evaluator Mode (QFP package)



- Note)** 1. NC (Pin 90) is always connected to VDD.  
 2. Vss (Pins 41 and 88) are both connected to GND.  
 3. MP (Pin 39) is always connected to GND.

Pin Assignment in Evaluator Mode (LQFP package)



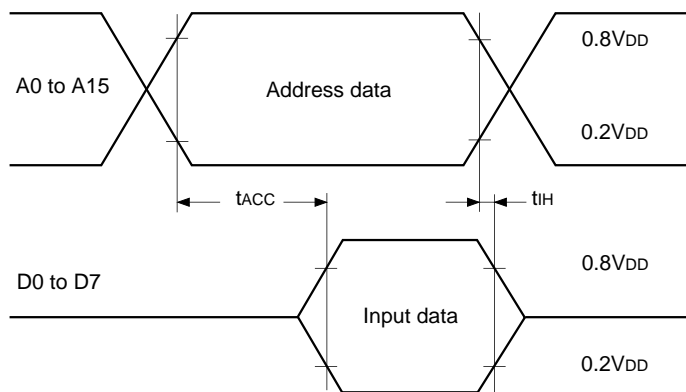
- Note)**
1. NC (Pin 88) is always connected to VDD.
  2. Vss (Pins 39 and 86) are both connected to GND.
  3. MP (Pin 37) is always connected to GND.

**EPROM Read Timing** ( $T_a = -20$  to  $+75^\circ\text{C}$ ,  $V_{DD} = 3.0$  to  $5.5\text{V}$ ,  $V_{SS} = 0\text{V}$ )

Item	Symbol	Pin	Min.	Max.	Unit
Address → data input delay time	$t_{ACC}$	A0 to A15 D0 to D7		100*1	ns
				75*2	
Address → data hold time	$t_{IH}$	A0 to A15 D0 to D7	0		ns

\*1 At 12MHz operation ( $V_{DD} = 4.5$  to  $5.5\text{V}$ )

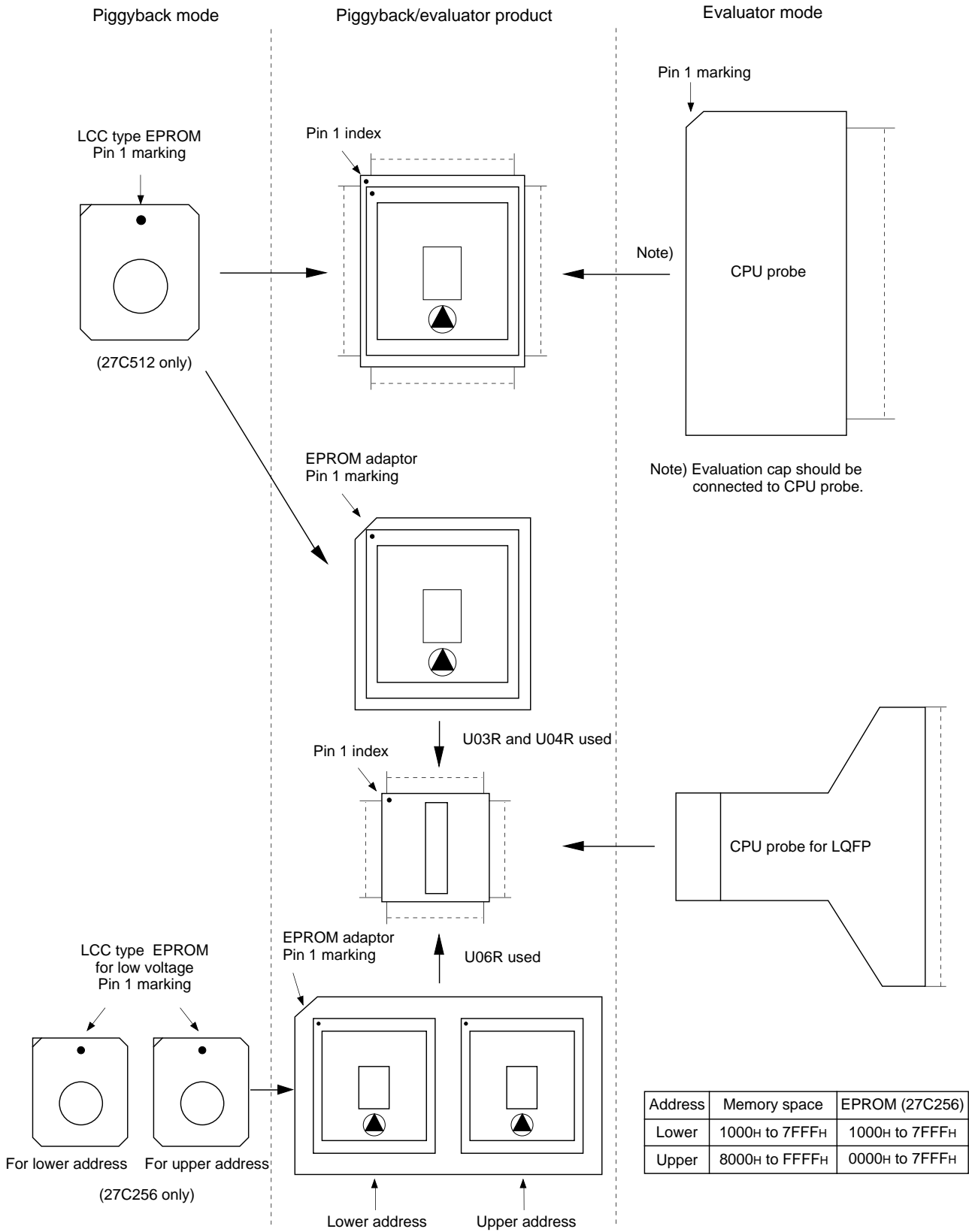
\*2 At 12MHz operation ( $V_{DD} = 3.0$  to  $5.5\text{V}$ ), At 16MHz operation ( $V_{DD} = 4.5$  to  $5.5\text{V}$ )



**Products List**

Option item	Products				
	Mask product		Piggyback/evaluator product		
	CXP81952	CXP81960	CXP81900-U03Q CXP81900-U03R	CXP81900-U04Q CXP81900-U04R	CXP81900-U06R
Package	100-pin plastic QFP/LQFP		100-pin ceramic PQFP		
ROM capacity	52Kbytes	60Kbytes	EPROM 60Kbytes		
			$27\text{C}512 \times 1$	$27\text{C}512 \times 1$	$27\text{C}256 \times 2$
Pull-up resistor for reset pin	Existent/Non-existent		Existent		
Supply voltage	3.0 to 5.5V		4.5 to 5.5V	3.0 to 5.5V	3.0 to 5.5V

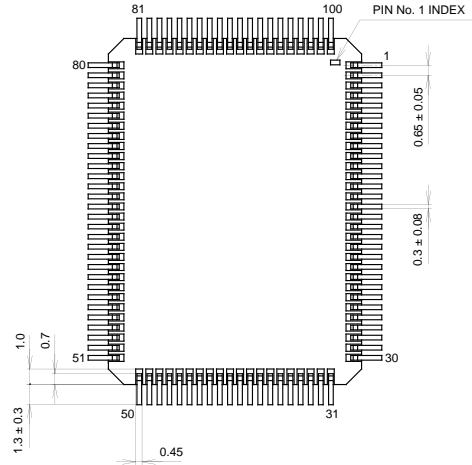
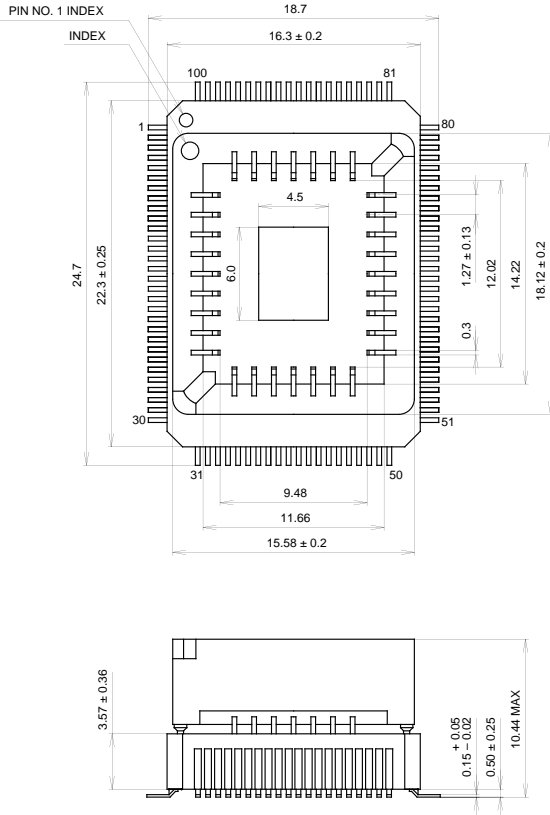
Piggyback mode/evaluator mode can be switched as shown below.



Address	Memory space	EPROM (27C256)
Lower	1000H to 7FFFH	1000H to 7FFFH
Upper	8000H to FFFFH	0000H to 7FFFH

Package Outline Unit: mm

100PIN PQFP (CERAMIC)

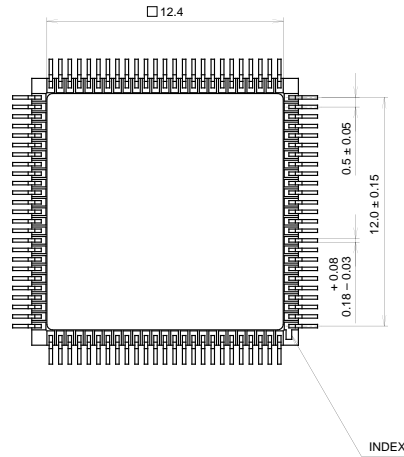
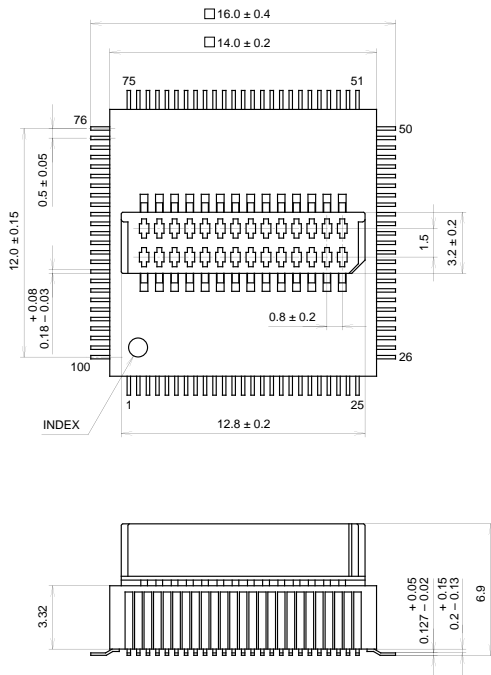


PACKAGE STRUCTURE

SONY CODE	PQFP-100C-L01
EIAJ CODE	AQFP100-C-0000-A
JEDEC CODE	

PACKAGE MATERIAL	CERAMIC
LEAD TREATMENT	GOLD PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	5.7g

100PIN PQFP (CERAMIC)



PACKAGE STRUCTURE

SONY CODE	PQFP-100C-L02
EIAJ CODE	AQFP100-C-1414-A
JEDEC CODE	

PACKAGE MATERIAL	CERAMIC
LEAD TREATMENT	GOLD PLATING
LEAD MATERIAL	42 ALLOY
PACKAGE WEIGHT	2.2g



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